



(1.27 mm) .050"

CLP-107-02-F-D-P

CLP-115-02-L-D

CLP-130-02-L-D

CLP-116-02-F-DH

CLP SERIES

# LOW PROFILE DUAL WIPE SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?CLP](http://www.samtec.com?CLP)

### Insulator Material:

Black Liquid Crystal Polymer

### Contact Material:

Phosphor Bronze

### Plating:

Sn or Au over

50 μ" (1.27 μm) Ni

### Current Rating (CLP/FTSH):

3.3 A per pin

(1 pin powered per row)

### Voltage Rating:

240 VAC/340 VDC

### Operating Temp Range:

-55 °C to +125 °C

### Contact Resistance:

10 mΩ

### Insertion Depth:

Top Entry = (1.40 mm) .055"

minimum, Bottom Entry =

(2.41 mm) .095" minimum

plus board thickness

DH Entry = (2.31 mm) .091"

to (2.67 mm) .105"

### Normal Force:

60 grams (0.59 N) average

### Max Cycles:

100 with 10 μ" (0.25 μm) Au

### RoHS Compliant:

Yes

## Mates with:

FTSH, FTS, FW

## APPLICATIONS

CLP FTSH

HORIZONTAL

PASS-THRU

High-reliability  
Tiger Claw™  
contacts

(1.27 mm x 1.27 mm)  
.050" x .050"  
micro pitch

Low profile  
(2.21 mm)  
.087"

Surface  
mount

Suitable for pass-through  
applications



## PROCESSING

### Lead-Free Solderable:

Yes

### SMT Lead Coplanarity:

(0.10 mm) .004" max (02-35)

(0.15 mm) .006" max (36-50)

## RECOGNITIONS

For complete scope of  
recognitions see  
[www.samtec.com/quality](http://www.samtec.com/quality)



## ALSO AVAILABLE (MOQ Required)

- Single row
  - Other platings
- Contact Samtec.

**Note:** Some sizes, styles and options are non-standard, non-returnable.

